## Nch 650V 24A Power MOSFET

$V_{DSS}$	650V
R <sub>DS(on)</sub> (Max.)	0.185Ω
I <sub>D</sub>	±24A
$P_D$	245W

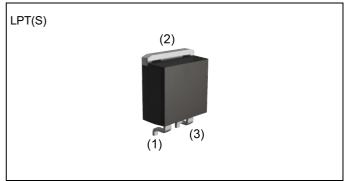
# ●Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

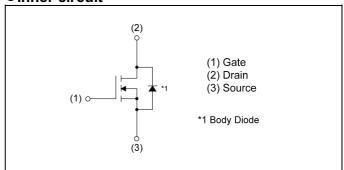
## Application

Switching

## Outline



## •Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6524ENJ
Basic ordering unit (pcs)	1000

## ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	650	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±24	А	
Pulsed drain current	I <sub>DP</sub> *2	±72	А	
Gate - Source voltage static AC(f>1Hz)			±20	V
		$V_{GSS}$	±30	V
Avalanche current, single pulse	·	I <sub>AS</sub>	4.1	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	654	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P <sub>D</sub>	245	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage temp	erature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Downwortow	Cymah al	Values			1.1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	0.51	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

## ●Electrical characteristics (T<sub>a</sub> = 25°C)

Davameter	Cymah al	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	-	V	
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ	
		$T_j = 125^{\circ}C$	ı	-	1000		
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	1	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 750 \mu A$	2	-	4	V	
		$V_{GS} = 10V, I_D = 11.3A$					
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.160	0.185	Ω	
		$T_j = 125^{\circ}C$	-	-	-		
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	6.5	-	Ω	

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darramatar	Cymah al	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1650	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	1850	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	220	-	
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	30	-	
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 12A	-	55	-	
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 27.4\Omega$	-	180	-	ns
Fall time	t <sub>f</sub> *6	$R_G = 10\Omega$	-	55	-	

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*6}$	V <sub>DD</sub> ≈ 300V	-	70	-	
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 24A	-	10	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6	V <sub>GS</sub> = 10V	-	35	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 24A	-	5.8	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 70mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit			
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	-	-	24	Α	
Pulsed source current	I <sub>SP</sub> *2	1C - 23 C	1	-	72	Α	
Source-Drain voltage	V <sub>SD</sub> *6	V <sub>GS</sub> = 0V, I <sub>S</sub> = 24A	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *6		-	540	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 24Α di/dt = 100Α/μs	-	9.5	-	μC	
Peak reverse recovery current	<sub>rr</sub> *6		-	35	-	Α	

Fig.1 Power Dissipation Derating Curve

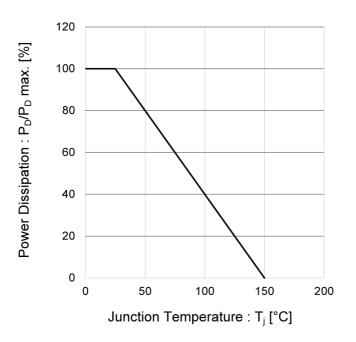


Fig.2 Drain Current Derating Curve

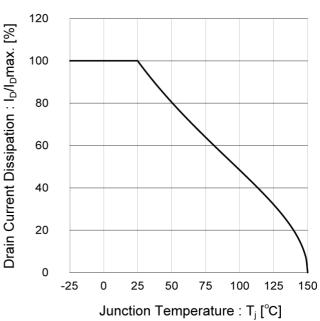


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

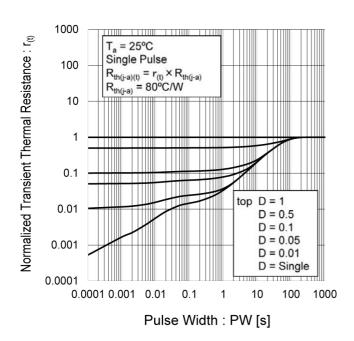
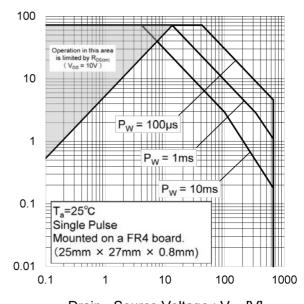


Fig.4 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

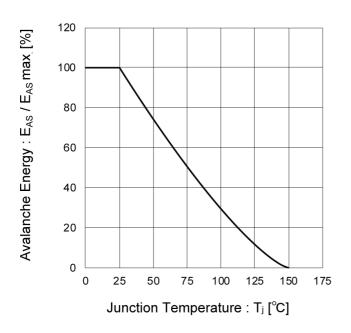


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

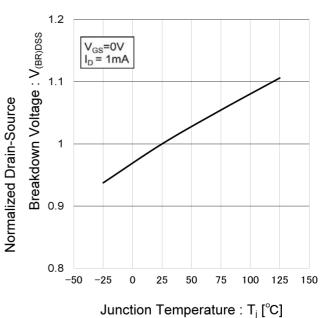


Fig.7 Typical Output Characteristics(I)

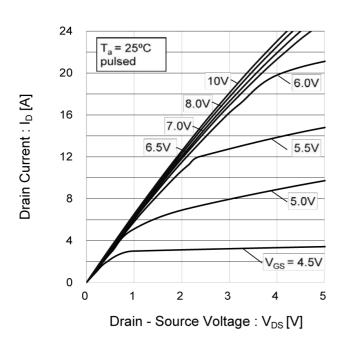
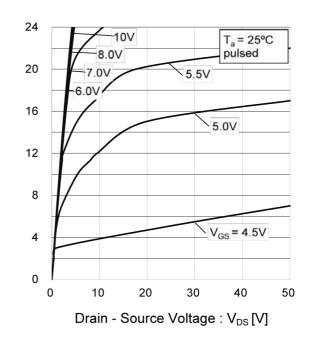


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

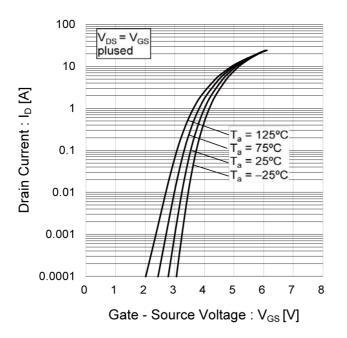


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

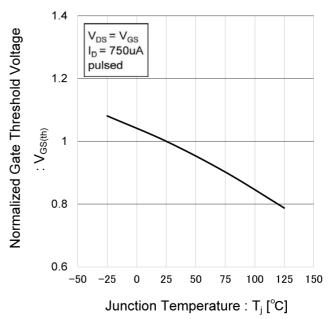


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

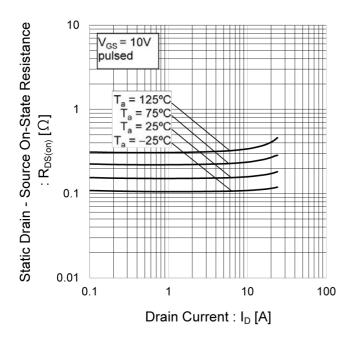


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

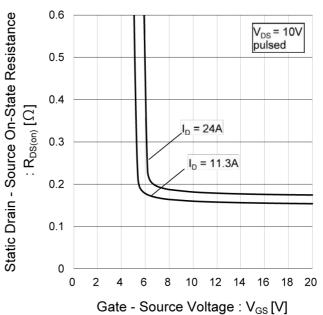


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

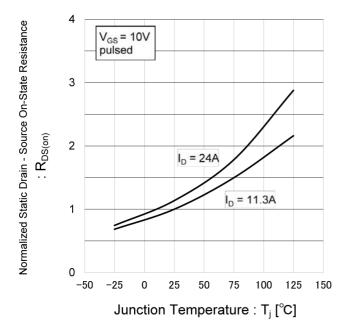


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

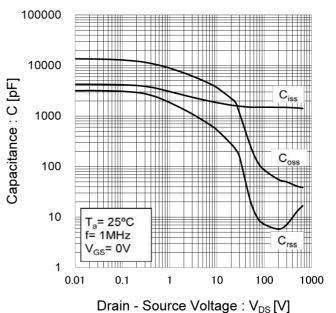


Fig.15 Switching Characteristics

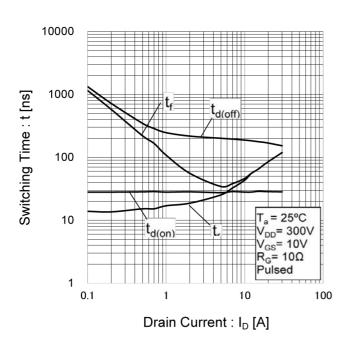
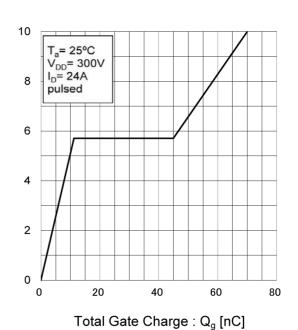


Fig.16 Typical Gate Charge



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

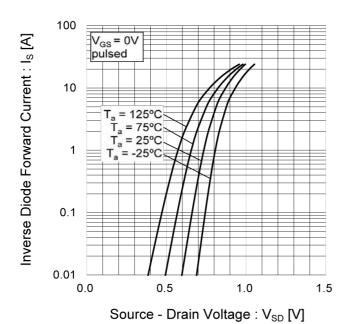
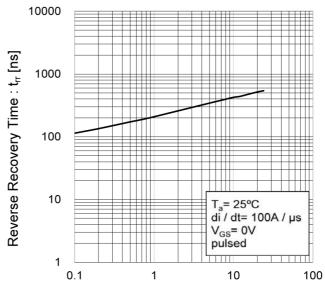


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current :  $I_S$  [A]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

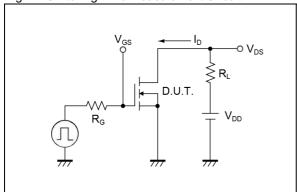


Fig.2-1 Gate Charge Measurement Circuit

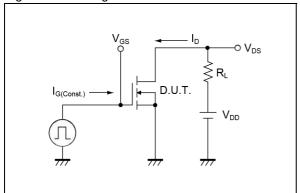


Fig.3-1 Avalanche Measurement Circuit

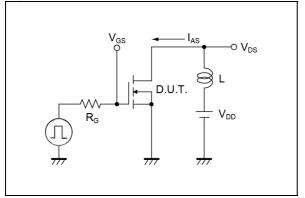


Fig.4-1 trr Measurement Circuit

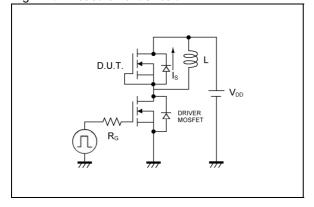


Fig.1-2 Switching Waveforms

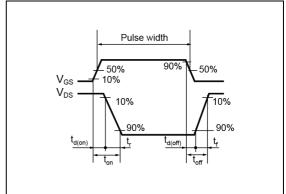


Fig.2-2 Gate Charge Waveform

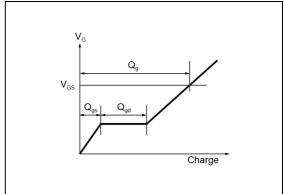


Fig.3-2 Avalanche Waveform

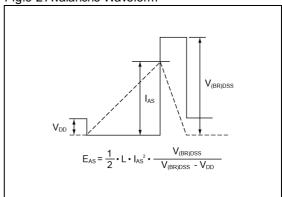
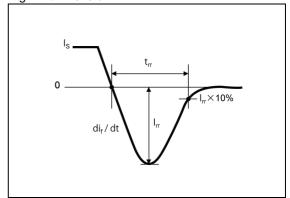
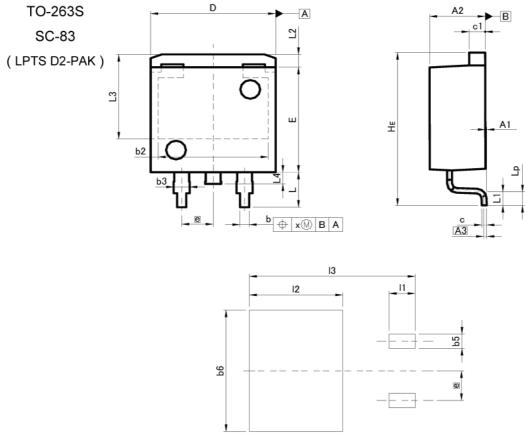


Fig.4-2 trr Waveform



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

TRA	MILIM	ETERS	INC	HES
IM	MIN	MAX	MIN	MAX
41	0.00	0.30	0.000	0.012
42	4.30	4.70	0.169	0.185
43	0.		0.0	
b	0.68	0.98	0.027	0.039
52		90	0.3	
53	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
:1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
e		54	0.1	
HE	12.80	13.40	0.504	0.528
	2.70	3.30	0.106	0.130
_1	1.	20	0.0	47
_2	1.	10	0.0	143
_3	7.	25	0.2	85
_4	1.	00	0.0	39
_p	0.90	1.50	0.035	0.059
х	= .	0.25		0.010
	2-28 V	0.23	TNO	

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
bb	=:	1.23	-	0.049
b6	<b>=</b> 0	10.40	<del></del>	0.409
11	23	2.10		0.083
12	<del>77</del> .4	7.55	1.00	0.297
13	-	13.40	3 <del></del>	0.528

Dimension in mm/inches



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CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
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  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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